

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. 09/714,714
Priority Filing Date November 15, 2000
Inventor Kardokus, J. et al
Assignee Honeywell International, Inc
Priority Group Art Unit 1742
Priority Examiner Ip, S
Attorney's Docket No. JM34006 DIV
Title: (As Amended) Methods of Forming Copper-Containing Sputtering Targets

2/A
C.7.
1/23/02

PRELIMINARY AMENDMENT

To: Box Patent Application
Assistant Commissioner for Patents
Washington, D.C. 20231

From: Jennifer J. Taylor, Ph.D. (Tel. 509-624-4276; Fax 509-838-3424)
Wells, St. John, Roberts, Gregory & Matkin P.S.
601 W. First Avenue, Suite 1300
Spokane, WA 99201-3828

1002992664200F

AMENDMENTS

In the Specification

- Please replace the Title with the following new Title:
K' --Methods of Forming Copper --Containing Sputtering Targets--

Before the "Background of the Invention" section, please add:

RELATED PATENT DATA

A² This patent resulted from a divisional application of U.S. Patent Application Serial
No. 09/714,714; which is a continuation application of U.S. Patent Application Serial No.